

Fig. 1

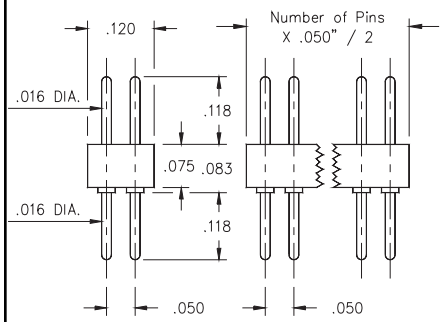


Fig. 2

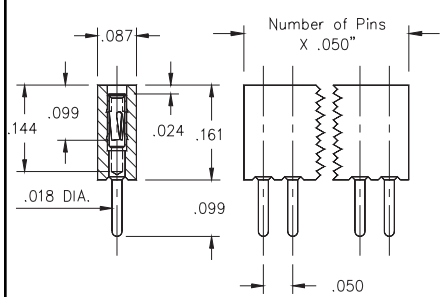


Fig. 3

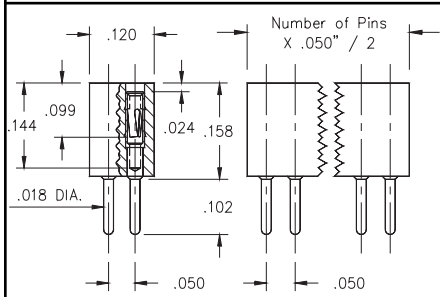


Fig. 4

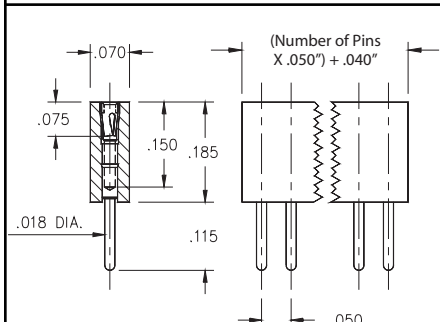
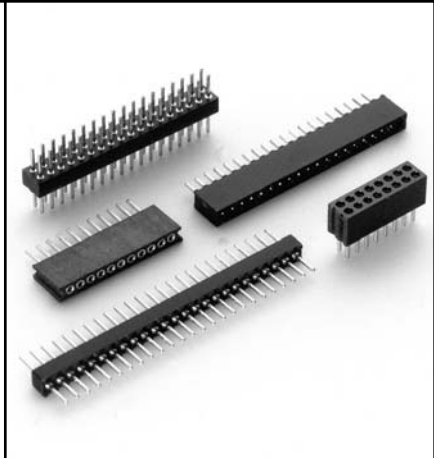


Fig. 5

- Series 850 single and double row interconnects have .050" pin spacing and permit board stacking as low as .248".
- Pin headers have .017" dia. pins. (MM# 3006 see page 166 for details).
- MM# 0489 and 0467 receptacles use M-M#11 Hi-Rel, 3-finger beryllium copper contacts rated at 3 amps. (#11 contact accepts pin diameters from .015-.020)
- Insulators are high temp. thermo-plastic, suitable for all soldering operations.



Ordering Information

Fig. 1	Single Row	.087" Profile Pin Header
	Specify # of pins	850-XX-0__-10-001 01-50
Fig. 2	Double Row	.075" Profile Pin Header
	Specify # of pins	852-XX-___-10-001 002-100

*XX= Plating Code
See Below*

SPECIFY PLATING CODE XX=	10	90		
Pin Plating	10μ" Au	200μ" Sn/Pb		

Fig. 3	Single Row	.161" Profile Socket
	Specify # of pins	851-XX-0__-10-001 01-50
Fig. 4	Double Row	.161" Profile Socket
	Specify # of pins	853-XX-___-10-001 002-100
Fig. 5	Single Row	.185" Profile Socket
	Specify # of pins	851-XX-0__-10-002 01-77

*XX= Plating Code
See Below*

SPECIFY PLATING CODE XX=		93	99
Sleeve (Pin)		200μ" Sn/Pb	200μ" Sn/Pb
Contact (Clip)		30μ" Au	200μ" Sn/Pb